

REMARKS

This responds to the Office Action mailed on November 10, 2004. By this amendment, claims 1, 2, 25 and 31-33 are amended and no claims are added or canceled. No new matter has been added by this amendment. Reconsideration of this application is requested in view of the above amendments and the below comments. Claims 1-35 remain pending in the application, and claims 9-23 are withdrawn.

Drawings

In the Office Action the Examiner required submission of new drawings. The Examiner noted that FIG. 6 did not include the reference number 600.

Corrected drawings are supplied herewith. Each of the figures was formalized. Reference number 600 was added to FIG. 6. Reference numbers were added to FIG. 4. Support for each of these amendments is found in the portion of the specification describing the corresponding Figure. No new matter has been added.

§112 Rejection of the Claims

Rejection: Claims 1-2 and 31-33 were rejected under 35 USC § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which Applicant regards as the invention.

Response: By this amendment the claims have been amended to overcome the rejections based on 35 USC § 112, second paragraph.

Objection of the Claims

A. Objection: The Examiner objected to claim 24 stating that the claim language “wherein cooling the die and substrate to a second temperature includes cooling the die and substrate from the first temperature to the second temperature without cooling to a temperature below the second temperature” was not described/supported in the specification.

B. Response: Applicant submits that this claim language is supported in the specification. Specifically, support for the claim language can be found at page 6, lines 6-15 as well as other places.

C. Objection: The Examiner objected to claim 25 stating that the claim language “wherein cooling the die, substrate and epoxy includes cooling the die, substrate and epoxy to a third temperature below the first temperature and the second temperature” was not described/supported in the specification.

D. Response: Applicant submits that this claim language is supported in the specification. Specifically, support for the claim language can be found at page 6, lines 6-15 as well as other places. The specification states that the “...die and substrate are not cooled to a temperature significantly below the second temperature until after the heated epoxy is placed in contact with the die and the substrate...” (see page 6, lines 10-12). The specification does not specifically refer to a third temperature but speaks to a temperature below the second temperature. If the Examiner requires that the mention of a third temperature be within the specification, Applicant will add the language.

E. Objection: The Examiner objected to claim 34 stating that the claim language “wherein cooling the die and substrate to a second temperature is done without adding heat to the die and substrate” was not described/supported in the specification.

F. Response: Applicant submits that this claim language is supported in the specification. Specifically, support for the claim language can be found at page 6, lines 12-15 as well as other places.

G. Objection: The Examiner objected to claim 35 stating that the claim language “further comprising adding heat to the die, substrate and epoxy to substantially maintain the second temperature” was not described/supported in the specification.

H. Response: Applicant submits that this claim language is supported in the specification. Specifically, support for the claim language can be found at page 6, lines 7-8 as well as other places. The specification states that the “...method 200 further includes holding the

die and substrate at the second temperature for a time sufficient to allow the epoxy to cure.”
(See page 6, lines 7-8). Claim 1 includes similar language. Claim 8 also speaks of maintaining the die and substrate at a second temperature. Generally, an object at a temperature tends to cool unless heat is added. For example, heat must be added to water in a pan to keep it boiling. If heat is not added, boiling discontinues. The only way to maintain or hold a temperature is by the addition of heat to the object.

Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney ((612) 373-6977) to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

SANDEEP B SANE ET AL.

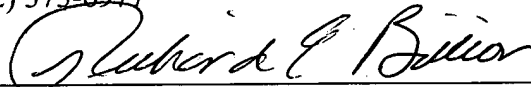
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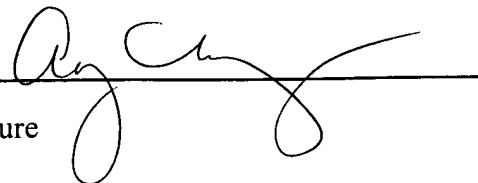
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 10th day of February, 2005.

Name

Amy Moriarty

Signature



IN THE DRAWINGS

Corrected drawings are supplied herewith. Each of the figures was formalized. Reference number 600 was added to FIG. 6. Reference numbers were added to FIG. 4. Support for each of these amendments is found in the portion of the specification describing the corresponding Figure. No new matter has been added.